

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1121cz-5#trpbf

(Engineering Calculation)

TO-92

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**TOTAL MASS (g) : 0.204809**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001703	1000000	8315.05664062		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.088433	975000	431782.34375		
		Iron (Fe)	7439-89-6	0.002177	24000	10629.4052734		
		Phosphorus (P)	7723-14-0	0.000027	300	131.83001709		
		Zinc (Zn)	7440-66-6	0.000063	700	307.603363037		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.090700</b>	<b>1000000</b>	<b>442851.1875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.005680	1000000	27734.1054688		
		<b>External Plating Total:</b>				<b>0.005680</b>	<b>1000000</b>	<b>27734.1054688</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000320	1000000	1562.4296875		
<b>Internal Plating Total:</b>				<b>0.000320</b>	<b>1000000</b>	<b>1562.4296875</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000617	750000	3012.55981445		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000206	250000	1005.81414795		
<b>Die Attach Total:</b>				<b>0.000823</b>	<b>1000000</b>	<b>4018.3737793</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.014243	135000	69542.7734375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.090730	860000	442997.65625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000528	5000	2578.0090332		
		<b>Encapsulation Total:</b>				<b>0.105501</b>	<b>1000000</b>	<b>515118.46875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000082	1000000	400.372650146		
					<b>TOTAL MASS (g) :</b>	<b>0.204809</b>		